

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TSUKASA KAMAKURA	07/04/2016
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<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15220979
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<b>NAME OF SUBMITTER:</b>	DANIEL N. CALDER
<b>SIGNATURE:</b>	/Daniel N. Calder/
<b>DATE SIGNED:</b>	07/27/2016
<b>Total Attachments: 3</b>	
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source=HITACHI13_0001112US01_AssignmentDeclaration_EFS#page2.tif	
source=HITACHI13_0001112US01_AssignmentDeclaration_EFS#page3.tif	

**ASSIGNMENT AND DECLARATION**

With respect to the invention titled

**SUBSTRATE PROCESSING APPARATUS, METHOD OF  
MANUFACTURING SEMICONDUCTOR DEVICE, AND RECORDING  
MEDIUM**

for which the undersigned has authorized or prepared an application for United States Letters Patent, U.S. Patent Application No. \_\_\_\_\_, filed on \_\_\_\_\_,

I (the undersigned) hereby state the following.

**DECLARATION**

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than 5 years, or both.

**ASSIGNMENT**

The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

Assignee	<u>HITACHI KOKUSAI ELECTRIC INC.</u>
Assignee State or Country of Incorporation	<u>Japan</u>
Assignee Address	<u>14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan</u>

Assignee is desirous of acquiring the entire right, title and interest in the invention, all applications for and all letters patent issued on the invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee and assignee's successors, assigns and legal representatives the entire right, title and interest in the invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, and all divisions and continuations thereof, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of the invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of the assignee, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrants that the rights and property herein conveyed are free and clear of any encumbrance.

AND this Assignment may be executed in multiple counterparts, each of which shall be deemed to be an original of this Assignment. Additionally, the undersigned hereby authorizes our attorneys to collect the signature pages of each executed counterpart and to attach those signature pages to a single copy of this instrument, which single copy and attached signature pages together shall constitute an original of this Assignment.

**SIGNATURE SHEET FOR  
DECLARATION AND ASSIGNMENT**

Inventor's Name KAMAKURA, Tsukasa  
Inventor's Signature *Tsukasa Kamakura*  
Date July 4, 2016  
Signed at Toyama-shi, Japan  
(City and Country)

**STATEMENT OF WITNESS (optional):**

I, \_\_\_\_\_  
Name of Witness

was personally present and did see KAMAKURA, Tsukasa  
inventor identified above

execute this Assignment on \_\_\_\_\_ and such Assignor is personally known  
date

to me to be the person described herein.

Witness  
Signature \_\_\_\_\_

An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use a separate form for each inventor; or check the box below and complete the attached page(s) to list additional inventors.

Additional inventors are being named on the \_\_\_\_ supplemental sheet(s) attached hereto.